



August 11, 2005

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/802,563 03/17/04

Hong Yu Yu et al

"A THERMAL ROBUST SEMICONDUCTOR
DEVICE USING HFN AS METAL GATE
ELECTRODE AND THE MANUFACTURING
PROCESS THEREOF"

Grp. Art Unit: 2823

SU C. KIM

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated May 27, 2005, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on August 29, 2005.

Rosemary L. S. Pike, Reg # 39,332

Signature

Date

Rosemary L. S. Pike
August 29, 2005

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of the Claims which begins on page 8 of this paper.

Amendments to the Drawings begin on page 16 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 17 of this paper.

An Appendix including amended drawing figures is attached following page 22 of this paper.